Heatsink compound

Product information

Heat Sink Compound is applied to the base and mounting studs of transistors, diodes and silicon-controlled rectifiers. It can also serve as an effective thermal coupler for many heat sink devices where efficient cooling is required. It is also suitable for aircraft engines where heat sink properties are required.

- A grease-like silicon material, thickened with heat conductive metal oxides
- High thermal conductivity with low bleed
- No drying, hardening or melting
- Stable at high temperatures
- Suitable for the base and mounting studs of transistors, diodes and effective many heat sink devices

Technical information

Colour	White
Bleed after 24 hr at 200°C (392°F)	0.05%
Evaporation after 24 hr at 200°C (392°F)	0.5%
Drop point	300°C (570°F)
Thermal conductivity, K factor	0.0014 cal/sec-cm-°C
Dielectric strength	210 volts/mil

Packing

Tubes of 100gr

Ordering code

*This datasheet is purely indicative, build-up of model code may vary from this datasheet.

Model	HSC 340

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